

Subsolidus phase equilibria in the $\text{RuO}_2\text{--ZnO--SiO}_2$ system

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Introduction

Thick-film resistors are made by screen-printing thick-film paste on insulating, mainly alumina, substrates. After printing and drying, the thick-film pastes are fired in a belt furnace. Thick-film resistor pastes consist basically of a conducting phase, a lead borosilicate-based glass phase and an organic vehicle. The organic material is burned out between 300 and 400 °C during the high-temperature processing. The ratio between the conductive and glass phases roughly determines the specific resistivity of the resistor. In most modern resistor compositions the conductive phase is either RuO_2 or ruthenates. The glass phase is based on the $\text{B}_2\text{O}_3\text{--PbO--SiO}_2$ glasses with the molar ratio of SiO_2/PbO approximately equal to 2. Some other oxides are also added as modifiers of the temperature coefficient of expansion and/or the glass-transition temperature [1–5].

The well-known European environmental legislation, i.e., the RoHS Directive (restriction of the use of certain hazardous substances), requires the elimination of the lead, or at least a minimising of the lead content in electrical and electronic equipment to below 0.1 wt.%—starting from July 2006. Thick-film materials are currently an exemption from the directive, but the producers of thick-film materials are already developing new material systems in accordance with the directive [6]. While there are many lead-free conductor and dielectric compositions available, the development of thick-film resistors with lead-free glasses is still mainly in the experimental stage. At least to the

authors' knowledge, no commercially available thick-film lead-free resistor series with characteristics comparable to “conventional” resistors is on the market.

However, many “experimental” papers have reported on the preparation and investigations of the characteristics of lead-free thick-film resistors where the conductive phase is based, like with “conventional” resistors, on ruthenium oxide or ruthenates [7–11]. In the glass phase the lead oxide is often replaced with the zinc oxide [12–15]. Regardless of the very different melting points (T_m is 886 and 1,975 °C for PbO and ZnO , respectively) both oxides share similar characteristics. Both PbO and ZnO are classified as intermediate oxides, i.e., they can be either glass formers or glass modifiers. Some of the characteristics, i.e., the dissociation energy per MO_x , the coordination number and the single bond strength, are summarised in Table 1 [16].

The aim of this work was to investigate subsolidus phase equilibria (in air) in the $\text{RuO}_2\text{--ZnO--SiO}_2$ system. The results would indicate possible interactions between silica-rich glass with the addition of ZnO and the conductive phase (ruthenium oxide) in lead-free thick-film resistors.

The binary Zn_2SiO_3 compound exists in the $\text{SiO}_2\text{--ZnO}$ system. The melting point of the eutectic on the ZnO -rich side is 1,507 °C, and on the SiO_2 -rich side it is 1,432 °C [17, 18]. Morimoto et al. reported a synthesis at a high temperature of 1,400 °C and at a high pressure, and a characterisation of the binary compound ZnSiO_3 [19]. Phase equilibria in the $\text{RuO}_2\text{--SiO}_2$ [5] and $\text{RuO}_2\text{--ZnO}$ systems were studied by Hrovat et al. [20]. In both systems there is no binary compound and no liquid phase (eutectic) at temperatures up to 1,405 °C, the temperature at which RuO_2 decomposes (in air) to metallic ruthenium and oxygen.

For the experimental work, RuO_2 (Ventron, 99.9%), ZnO (Johnson Matthey, ultrapure), and SiO_2 (Riedel de

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Table 1 Some of the characteristics of PbO and ZnO as intermediate oxides in glasses [16]

	Coordination number	Dissociation energy per MO _x (kJ/g-atom)	Single bond strength (kJ/g-atom)
PbO	2	607	305
ZnO	2	603	301

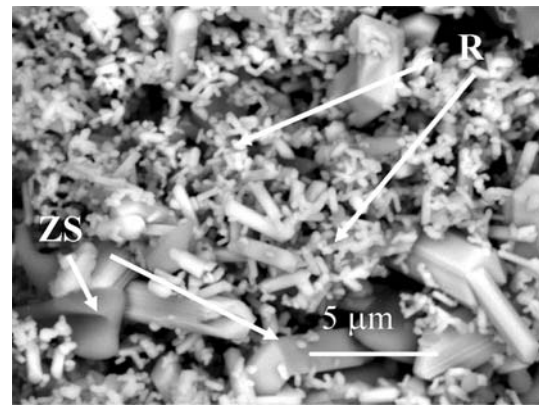
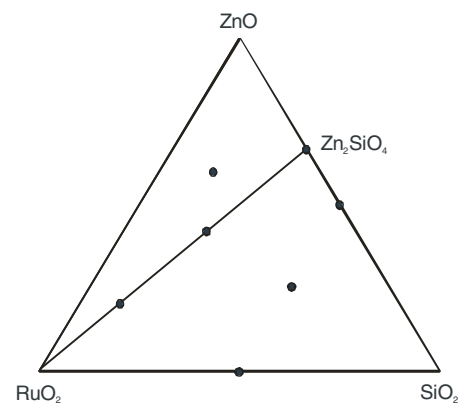
Haen, 99.9%) were used. The oxides were mixed in isopropyl alcohol, pressed into pellets, and fired up to five times in air with intermediate grinding. Three batches of samples were prepared for each composition. Samples in the RuO₂–ZnO–SiO₂ system were fired at 1,000 °C and in the ZnO–SiO₂ system they were fired at 1,200 °C. During firing the pellets were placed on platinum foils. The compositions of the relevant samples are shown in Fig. 2. The fired materials were characterised by X-ray powder-diffraction analysis using a Philips PW 1710 X-ray diffractometer with Cu K_α radiation. The X-ray spectra were measured from 2θ = 20° to 2θ = 70° in steps of 0.02°. A JEOL 5800 scanning electron microscope (SEM) equipped with an ISIS 300 energy-dispersive X-ray analyser (EDS) was used for the overall microstructural and compositional analysis. Prior to analysis in the SEM, the samples were sputtered with a carbon film to provide electrical conductivity and avoid charging effects.

The results of the X-ray powder analysis of the relevant samples, fired in air at 1,000 °C in the RuO₂–ZnO–SiO₂ system and at 1,200 °C in the binary ZnO–SiO₂ binary system are summarised in Table 2. The nominal compositions of the samples and the phases identified after firing are included.

The microstructure of the fractured cross-section of the sample with the nominal composition 2 RuO₂ + SiO₂ + 2 ZnO, fired at 1,000 °C, is shown in Fig. 1. The material was poorly sintered, so a polished cross-section could not be prepared. The sample is a two-phase mixture of RuO₂ (smaller grains) and the Zn₂SiO₄ (larger grains). Some of the RuO₂ and Zr₂SiO₄ grains are labelled “R” and “ZS”,

Table 2 Results of X-ray diffraction analysis of some compositions in the RuO₂–ZnO–SiO₂ system

Nominal composition	Phases identified
RuO ₂ + SiO ₂	RuO ₂ + SiO ₂
SiO ₂ + 2 ZnO	Zn ₂ SiO ₄
SiO ₂ + ZnO	Zn ₂ SiO ₄ + SiO ₂
2 RuO ₂ + SiO ₂ + 2 ZnO	RuO ₂ + Zn ₂ SiO ₄
7 RuO ₂ + SiO ₂ + 2 ZnO	RuO ₂ + Zn ₂ SiO ₄
5 RuO ₂ + 3 SiO ₂ + 12 ZnO	RuO ₂ + Zn ₂ SiO ₄ + ZnO
RuO ₂ + 2 SiO ₂ + ZnO	RuO ₂ + Zn ₂ SiO ₄ + SiO ₂

**Fig. 1** Microstructure of the fractured cross-section of a sample with the nominal composition 2 RuO₂ + SiO₂ + 2 ZnO, fired at 1,000 °C. The material is a two-phase mixture of RuO₂ (smaller grains) and Zn₂SiO₄ (larger grains). The RuO₂ and Zr₂SiO₄ grains are labelled “R” and “ZS”, respectively Back scattered electrons**Fig. 2** The proposed RuO₂–ZnO–SiO₂ subsolidus phase diagram. The tie line is between RuO₂ and Zn₂SiO₄. The compositions of the relevant samples are denoted by circles

respectively. Based on the results obtained by XRD and EDS, a subsolidus RuO₂–ZnO–SiO₂ phase diagram, shown in Fig. 2, was constructed. No ternary compound was found in the system. The tie line is between RuO₂ and Zn₂SiO₄. The ZnSiO₃ compound was not detected under the described synthesis conditions. The results indicate that the RuO₂, as a conductive phase in PbO-free thick-film resistors, is compatible with the SiO₂ and ZnO components of the glass phase.

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